Datasheet



N-channel SiC power MOSFET

V_{DSS}	750V
R _{DS(on)} (Typ.)	13mΩ
I _D ^{*1}	98A
P_{D}	267W

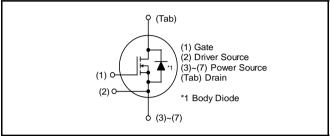
●Outline



Features

- 1) Low on-resistance
- 2) Fast switching speed
- 3) Fast reverse recovery
- 4) Easy to parallel
- 5) Simple to drive
- 6) Pb-free lead plating; RoHS compliant

●Inner circuit



Please note Driver Source and Power Source are not exchangeable. Their exchange might lead to malfunction.

Application

- Solar inverters
- DC/DC converters
- Switch mode power supplies
- · Induction heating

Packaging specifications

	Packing	Embossed tape
	Reel size (mm)	330
Typo	Tape width (mm)	24
Type	Basic ordering unit (pcs)	1000
	Taping code	TL
	Marking	SCT4013DW7

● **Absolute maximum ratings** (T_{vi} = 25°C unless otherwise specified.)

Parameter		Symbol	Value	Unit	
Drain - source voltage		V_{DSS}	750	V	
Continuous drain	$V_{GS} = V_{GS_on}$	$T_c = 25^{\circ}C$	I _D , I _S *1	98	А
and source current	V _{GS} = V _{GS_on}	T _c = 100°C	I _D , I _S	69	А
Pulsed drain current	$V_{GS} = V_{GS_on}$	$T_c = 25^{\circ}C$	I _{D,pulse} *2	233	Α
Body diode pulsed forward current T _c = 25°C		I _{S,pulse} *1,*3	98	Α	
Body diode surge forward current V _{GS} = 0 V		I _{S,pulse} *1,*4	233	Α	
Gate - source voltage (DC)		V_{GSS_DC}	-4 to +21	V	
Gate - source surge voltage (t _{surge} < 300ns)		V _{GSS_surge} *5	-4 to +23	V	
Recommended turn-on gate - source drive voltage		$V_{\rm GS_on}^{*6}$	+15 to +18	V	
Recommended turn-off gate - source drive voltage		V_{GS_off}	0	V	
Virtual junction temperature		T_{vj}	175	°C	
Range of storage temperature		T_{stg}	-40 to +175	°C	

ullet Electrical characteristics (T_{vj} = 25°C unless otherwise specified)

Doromotor	Symbol	Conditions		Values	Unit	
Parameter	Symbol Conditions —		Min.	Тур.	Max.	Offic
Drain - Source breakdown voltage	W	$V_{GS} = 0 \text{ V}, I_D = 18.6\text{mA}$				V
	V (BR)DSS	$T_{vj} = 25^{\circ}C$	750	-	-	V
		$V_{GS} = 0 \text{ V}, V_{DS} = 750 \text{V}$				
Zero Gate voltage Drain current	I _{DSS}	$T_{vj} = 25^{\circ}C$	-	1	80	μA
Diam ourion		T _{vj} = 150°C	-	10	-	
Gate - Source leakage current	I _{GSS+}	$V_{GS} = +21V , V_{DS} = 0V$	-	-	100	nA
Gate - Source leakage current		$V_{GS} = -4V$, $V_{DS} = 0V$	-	-	-100	nA
Gate threshold voltage	$V_{GS(th)}^{*7}$	$V_{DS} = 10V, I_D = 30.8 \text{mA}$	2.8	ı	4.8	V
		$V_{GS} = 18V, I_{D} = 58A$				
Static Drain - Source on - state resistance	R _{DS(on)} *8	$T_{vj} = 25^{\circ}C$	-	13.0	16.9	mΩ
on one of the order		T _{vj} = 150°C	-	22.2	-	
Gate input resistance	R_{G}	f = 1MHz, open drain	-	1	-	Ω

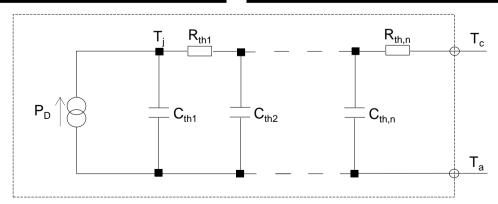
●Thermal resistance

Parameter	Symbol	Values			Unit
		Min.	Тур.	Max.	Offic
Thermal resistance, junction - case	R _{thJC} *9	-	0.43	0.56	K/W

●Typical Transient Thermal Characteristics

Symbol	Value	Unit
R _{th1}	4.1 ×10 ⁻²	
R _{th2}	1.8 ×10 ⁻¹	K/W
R _{th3}	2.1 ×10 ⁻¹	

Symbol	Value	Unit
C_{th1}	1.2 ×10 ⁻³	
C_{th2}	5.0 × 10 ⁻³	Ws/K
C _{th3}	4.7 ×10 ⁻²	



ullet Electrical characteristics (T_{vj} = 25°C unless otherwise specified)

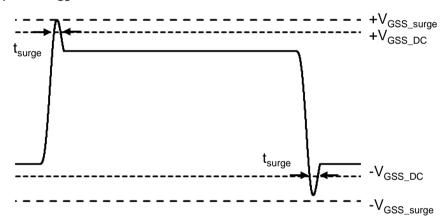
Davamatar	Cymah al	Conditions		Values		
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Transconductance	g _{fs} *8	$V_{DS} = 10V, I_{D} = 58A$	-	32	-	S
Input capacitance	C _{iss}	V _{GS} = 0V	-	4580	-	
Output capacitance	C _{oss}	V _{DS} = 500V	-	203	-	pF
Reverse transfer capacitance	C_{rss}	f = 1MHz	-	10	-	ı
Effective output capacitance, energy related	C _{o(er)}	$V_{GS} = 0V$ $V_{DS} = 0V \text{ to } 500V$	-	263	-	pF
Total Gate charge	Q _g *8	$V_{DS} = 500V$ $I_{D} = 58A$	-	170	-	
Gate - Source charge	Q _{gs} *8	$V_{GS} = 18V$	-	39	1	nC
Gate - Drain charge	Q _{gd} *8	See Fig. 1-1, 1-2.	-	42	-	
Turn - on delay time	t _{d(on)} *8	$V_{DS} = 500V$ $I_{D} = 58A$	-	17	-	
Rise time	t _r *8	$V_{GS} = +18V / 0V$	-	32	-	nc
Turn - off delay time	t _{d(off)} *8	$R_G = 6.8\Omega$, L = 250µH E_{on} includes diode	-	82	-	ns
Fall time	t _f *8	reverse recovery $L_{\sigma} = 50 \text{nH}, C_{\sigma} = 10 \text{pF}$	-	17	-	
Turn - on switching loss	E _{on} *8	See Fig. 2-1, 2-2, 2-3.	ı	500	ı	1
Turn - off switching loss	E _{off} *8		-	310	-	μJ
$V_{GS(on)} = +15V$ Short-circuit	. t _{sc} *9	$V_{DS} \le 400V$ $V_{DS,peak} \le 750V$	-	12.0	-	μs
withstand time $V_{GS(on)} = +18V$		$T_{vj(start)} = 25^{\circ}C$ $R_G = 2.2\Omega$	-	11.5	-	μs

●Body diode electrical characteristics (Source-Drain) (T_{vi} = 25°C unless otherwise specified)

Dorometer	Symbol	ymbol Conditions	Values			l lm:4
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Forward voltage	V _{SD} *8	$V_{GS} = 0V, I_{S} = 58A$	ı	3.3	ı	V
Reverse recovery time	t _{rr} *8	$I_F = 58A$ $V_R = 500V$	ı	16	ı	ns
Reverse recovery charge	Q _{rr} *8	di/dt = 3300A/µs	ı	290	ı	nC
Peak reverse recovery current	I _{rrm} *8	$L_{\sigma} = 50$ nH, $C_{\sigma} = 10$ pF See Fig. 3-1, 3-2.	-	36	ı	А

^{*1} Limited by maximum T_{vi} and for Max. R_{thJC} .

*5 Example of acceptable V_{GS} waveform



Please note especially when using driver source that V_{GSS_surge} must be in the range of absolute maximum rating.

- *6 Please be advised not to use SiC-MOSFETs with V_{GS} below 10V as doing so may cause thermal runaway.
- *7 Tested after applying $V_{GS} = 21V$ for 100ms.
- *8 Pulsed
- *9 The value is based on TO-247 package. Single Pulsed.
- *10 Measured conformable to JESD51-14.

See the application note "rthjc_measurement_and_usage_an-e.pdf". Link

URL: https://fscdn.rohm.com/en/products/databook/applinote/discrete/common/rthjc_measurement_and_usage_an-e.pdf

^{*2} Pulse width and duty cycle are limited by T_{vj,max}.

^{*3} Only for body-diode, Repititive pulse, PW ≤ 1.5µs, Duty cycle ≤ 5%

^{*4} When used as a protective function, PW ≤ 10µs

Fig.1 Power Dissipation Derating Curve

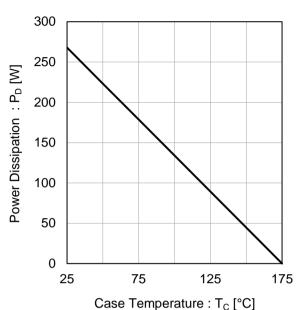


Fig.2 Maximum Safe Operating Area

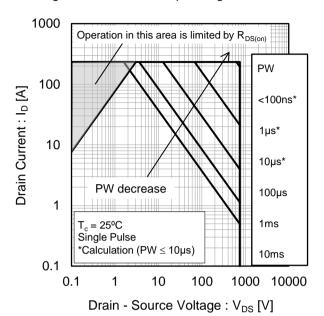
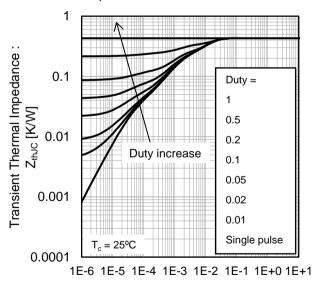


Fig.3 Typical Transient Thermal Impedance vs. Pulse Width



Pulse Width: PW [s]

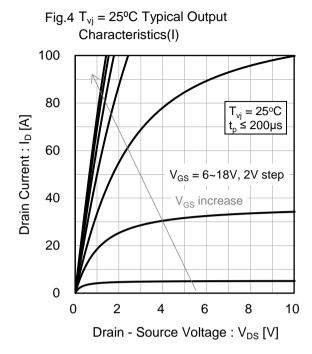
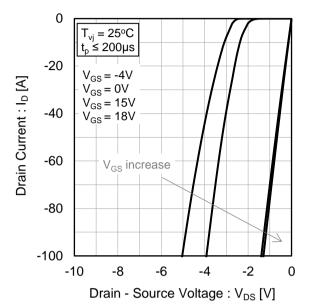
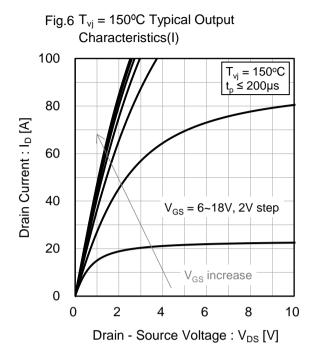
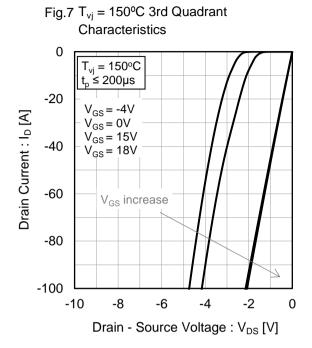


Fig.5 T_{vj} = 25°C 3rd Quadrant Characteristics







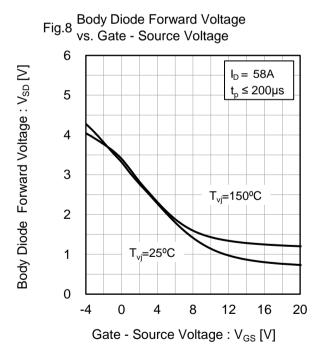


Fig.9 Typical Transfer Characteristics (I)

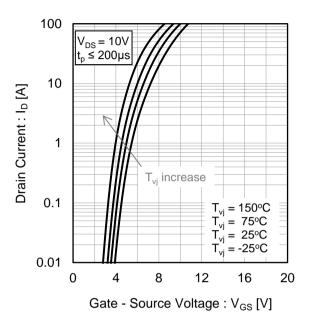


Fig.10 Typical Transfer Characteristics (II)

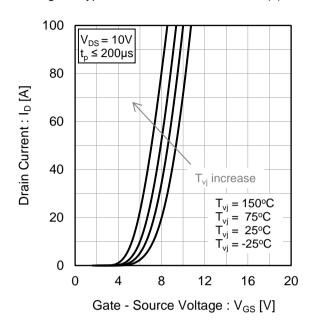


Fig.11 Gate Threshold Voltage vs. Virtual Junction Temperature

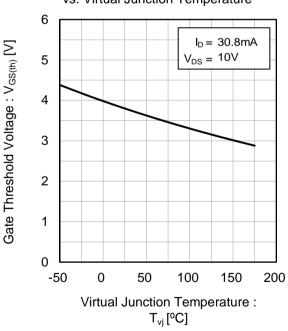
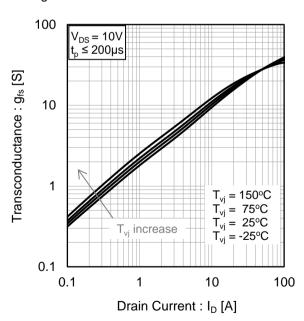
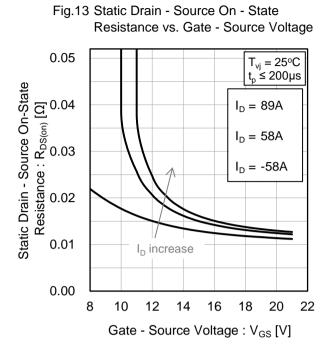


Fig.12 Transconductance vs. Drain Current

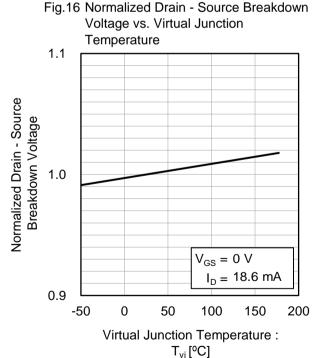


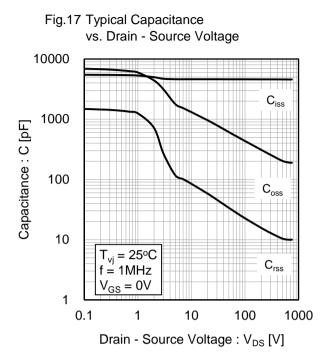


Resistance vs. Virtual Junction Temperature 0.05 $V_{GS} = 18V$ $t_p \le 200 \mu s$ Static Drain - Source On-State $I_{D} = 89A$ = 58A $I_{D} = -58A$ 0.01 I_D increase 0.00 -50 0 50 100 150 200 Virtual Junction Temperature: T_{vi} [°C]

Fig.14 Static Drain - Source On - State

Fig.15 Static Drain - Source On - State Resistance vs. Drain Current = 150°C $T_{vi} = 125^{\circ}C$ Static Drain - Source On-State $T_{vj} = 75^{\circ}C$ = 25°C Resistance: R_{DS(on)} [Ω] = -25°C 0.1 0.01 T_{vi} increase $V_{GS} = 18V$ $t_p \le 200 \mu s$ 0.001 10 100 Drain Current: I_D [A]





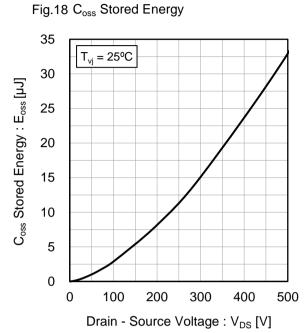


Fig.19 Dynamic Input Characteristics

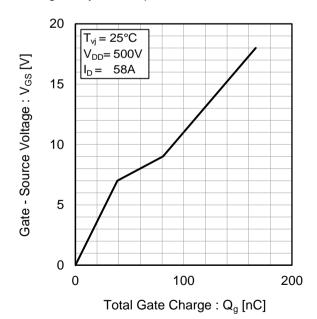


Fig.20 Typical Switching Time

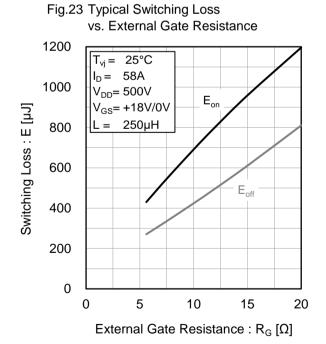
vs. External Gate Resistance 200 $T_{vi} = 25^{\circ}C$ $I_D = 58A$ V_{DD}= 500V $t_{d(off)}$ 150 V_{GS}= +18V/0V Switching Time: t [ns] $L = 250 \mu H$ 100 į t_r 50 0 5 10 15 20

External Gate Resistance : $R_G[\Omega]$

vs. Drain - Source Voltage 1200 $T_{vi} = 25^{\circ}C$ 58A 1000 V_{GS}= +18V/0V Switching Loss: E [µJ] $R_G = 6.8\Omega$ $L = 250 \mu H$ 800 600 E_{on} 400 200 E_{off} 0 100 200 300 500 400 Drain - Source Voltage: V_{DS} [V]

Fig.21 Typical Switching Loss

Fig.22 Typical Switching Loss vs. Drain Current 1200 $T_{vj} =$ 25°C V_{DD}= 500V 1000 V_{GS} = +18V/0V $R_G = 6.8\Omega$ Switching Loss : E [µJ] 250µH L= 800 600 400 $\mathsf{E}_{\mathsf{off}}$ 200 0 0 20 40 60 80 100 Drain Current: I_D [A]



• Measurement circuits and waveforms

Fig.1-1 Gate Charge Measurement Circuit

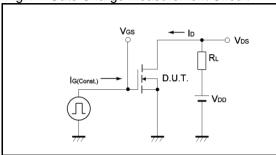


Fig.2-1 Switching Characteristics Measurement Circuit

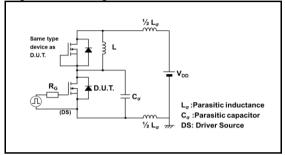


Fig.2-3 Waveforms for Switching Energy Loss

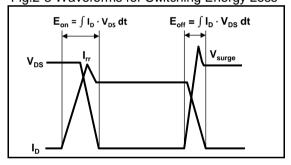


Fig.3-1 Reverse Recovery Time Measurement Circuit

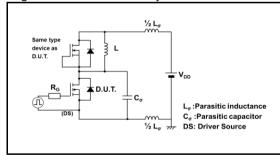


Fig.1-2 Gate Charge Waveform

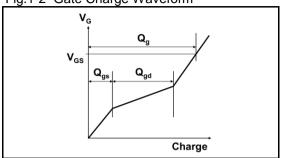


Fig.2-2 Waveforms for Switching Time

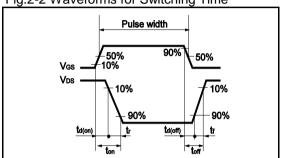
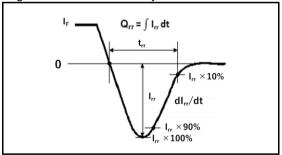
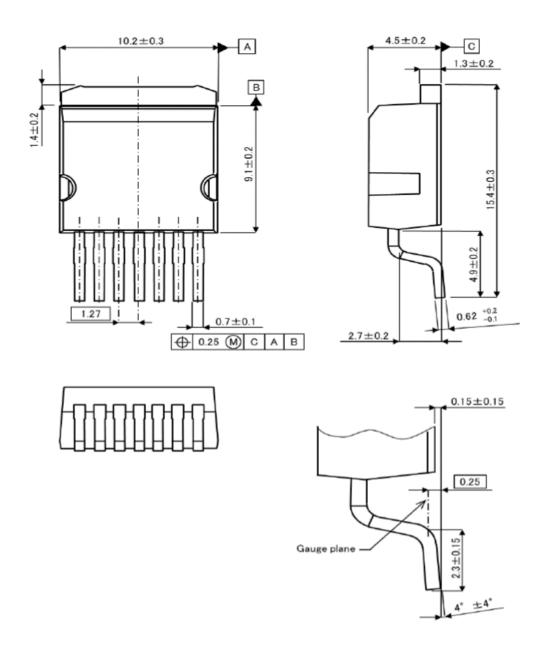


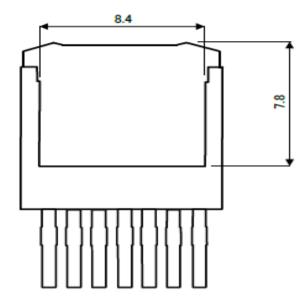
Fig.3-2 Reverse Recovery Waveform



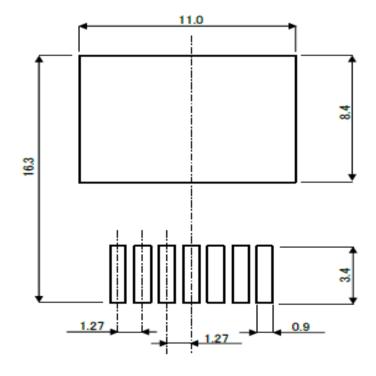
●Package Dimensions



Unit: mm

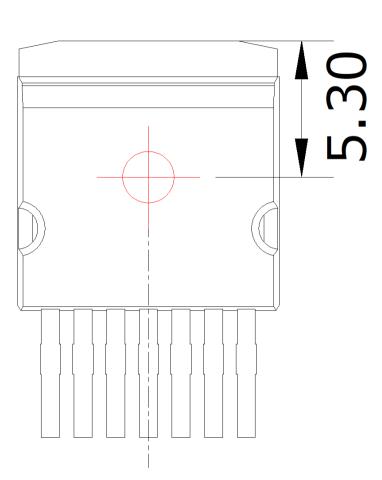


RECOMMENDED FOOTPRINT DIMENSIONS



Unit: mm

●Die Bonding Layout





- •Front view of the packaging.
- •Dimensions are design values.
- ·If the heat sink is to be installed, it should be in contact with the die bonding point.

Unit: mm

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